

L Number	Hits	Search Text	DB	Time stamp
1	3634	324/754.ccls. or 324/758.ccls. or 324/765.ccls. and (contact same attachment same electromagnet)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/13 11:53
2	72	(324/754.ccls. or 324/758.ccls. or 324/765.ccls. and (contact same attachment same electromagnet)) and (apparatus adj5 probing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/13 12:11
3	3	((324/754.ccls. or 324/758.ccls. or 324/765.ccls. and (contact same attachment same electromagnet)) and (apparatus adj5 probing)) and electromagnet	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/13 12:12
4	109	324/758.ccls. and (contact with mechanism)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/13 14:16
5	0	324/354.ccls. and (contact with mechanism)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/13 14:19
6	96938	contact with mechanism	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/13 14:17
7	56	324/354.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/13 14:18
8	0	324/754.ccls	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/13 14:19
9	237	324/754.ccls. and (contact with mechanism)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/13 14:20
-	166804	((removing or removed or subtracting or subtracted or reducing or reduced)with substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/03 10:18
-	53138	((removing or removed or subtracting or subtracted or reducing or reduced)with substrate)) and (heat or temperture)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/03 10:19
-	9052	((removing or removed or subtracting or subtracted or reducing or reduced)with substrate)) and (heat or temperture)) and (testing or test or tested) and (semiconductor or circuit or chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/03 10:21
-	1115	((removing or removed or subtracting or subtracted or reducing or reduced)with substrate)) and (heat or temperture)) and (testing or test or tested) and (semiconductor or circuit or chip)) and (liquid adj1 crystal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/03 10:22

-	267	(((((removing or removed or subtracting or subtracted or reducing or reduced)with substrate)) and (heat or temperture)) and (testing or test or tested) and (semiconductor or circuit or chip)) and (liquid adj1 crystal)) and (image and (defect or flaw))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/03 10:24
-	204	(((((removing or removed or subtracting or subtracted or reducing or reduced)with substrate)) and (heat or temperture)) and (testing or test or tested) and (semiconductor or circuit or chip)) and (liquid adj1 crystal)) and (image and (defect or flaw))) and (substrate with (removal or removed or removing))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/03 10:26
-	3106	324/754.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/12 14:53
-	747	324/758.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/13 13:08
-	3027	324/765.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/12 14:53
-	6438	324/754.ccls. or 324/758.ccls. or 324/765.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/13 11:51
-	669	(automated and camera and (contact adj3 surface) and alignment)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/12 15:04
-	15	(324/754.ccls. or 324/758.ccls. or 324/765.ccls.) and ((automated and camera and (contact adj3 surface) and alignment))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/12 14:57
-	3048	(camera and (contact adj3 surface) and alignment)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/12 15:05
-	56	(324/754.ccls. or 324/758.ccls. or 324/765.ccls.) and ((camera and (contact adj3 surface) and alignment))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/12 15:23
-	286	324/758.cor.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/12 15:40
-	219	324/754.ccls. and 324/758.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/12 15:57
-	1	6404212.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/12 15:57